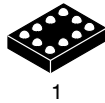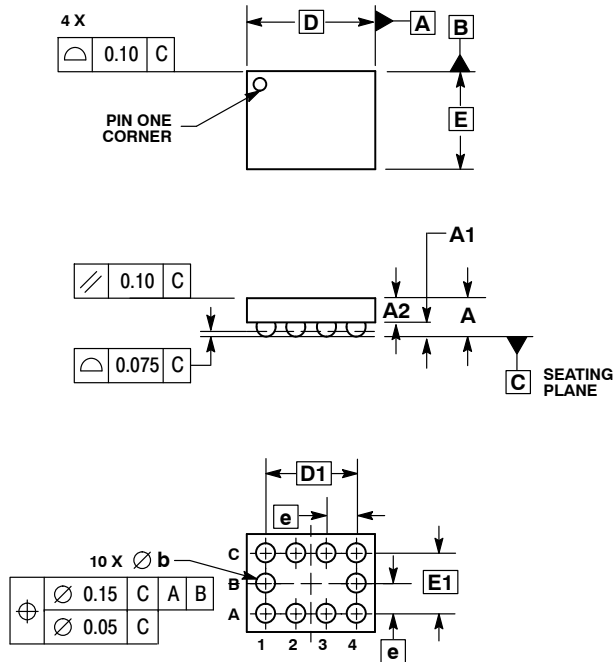**10 PIN FLIP−CHIP**
CASE 489AA
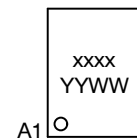ISSUE A

1

SCALE 4:1

DATE 04 MAY 2004

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	**MAX**
A	–––	0.650
A1	0.210	0.270
A2	0.280	0.380
D	1.965 BSC	
E	1.465 BSC	
b	0.250	0.350
e	0.500 BSC	
D1	1.500 BSC	
E1	1.000 BSC	

4 X

□ 0.10 C

PIN ONE CORNER

D A B

E

// 0.10 C

A1

A2 A

□ 0.075 C

SEATING PLANE
C

D1

e

10 X ⌀ b

⊕ ⌀ 0.15 C A B

⌀ 0.05 C

C
B
A

1 2 3 4

E1

e

GENERIC MARKING DIAGRAM*

xxxx
YYWW

A1 O

xxxx = Specific Device Code
YY = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot " ▪ ", may or may not be present.

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